

CM150TL-24NF

HIGH POWER SWITCHING USE

CM150TL-24NF



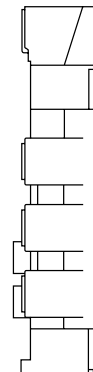
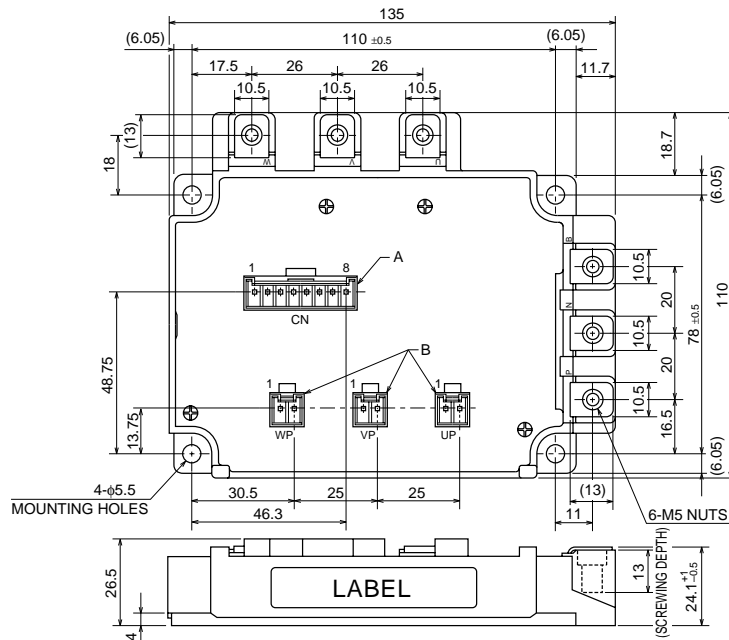
- Ic 150A
- VCES 1200V
- Insulated Type
- 6-elements in a pack

APPLICATION

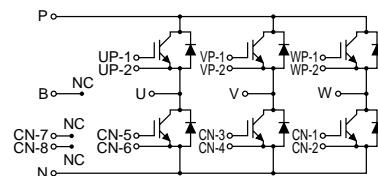
AC drive inverters & Servo controls, etc

OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



Housing Type of A and B
(J.S.T.Mfg.Co.Ltd)
A = B8P-VH-FB-B, B = B2P-VH-FB-B



CIRCUIT DIAGRAM

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ABSOLUTE MAXIMUM RATINGS (Tj = 25°C)

Symbol	Parameter	Conditions	Ratings	Unit
VCES	Collector-emitter voltage	G-E Short	1200	V
VGES	Gate-emitter voltage	C-E Short	±20	V
IC	Collector current	DC, Tc = 76°C*1	150	A
ICM		Pulse (Note 2)	300	A
IE (Note 1)	Emitter current		150	A
IEM (Note 1)		Pulse (Note 2)	300	A
PC (Note 3)	Maximum collector dissipation	Tc = 25°C	890	W
Tj	Junction temperature		−40 ~ +150	°C
Tstg	Storage temperature		−40 ~ +125	°C
Viso	Isolation voltage	Main Terminal to base plate, AC 1 min.	2500	V
—	Torque strength	Main Terminal M5	2.5 ~ 3.5	N • m
—		Mounting holes M5	2.5 ~ 3.5	N • m
—	Weight	Typical value	750	g

ELECTRICAL CHARACTERISTICS (Tj = 25°C)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
ICES	Collector cutoff current	VCE = VCES, VGE = 0V	—	—	1	mA
VGE(th)	Gate-emitter threshold voltage	IC = 15mA, VCE = 10V	6	7	8	V
IGES	Gate leakage current	VGE = VGES, VCE = 0V	—	—	0.5	μA
VCE(sat)	Collector-emitter saturation voltage	IC = 150A, VGE = 15V	—	2.1	3.0	V
		Tj = 25°C	—	2.4	—	
Cies	Input capacitance	VCE = 10V VGE = 0V	—	—	23	nF
Coēs	Output capacitance		—	—	2	nF
Cres	Reverse transfer capacitance		—	—	0.45	nF
QG	Total gate charge	VCC = 600V, IC = 150A, VGE = 15V	—	675	—	nC
td(on)	Turn-on delay time	VCC = 600V, IC = 150A VGE1 = VGE2 = 15V RG = 2.1Ω, Inductive load switching operation IE = 150A	—	—	130	ns
tr	Turn-on rise time		—	—	70	ns
td(off)	Turn-off delay time		—	—	400	ns
tf	Turn-off fall time		—	—	350	ns
t _{rr} (Note 1)	Reverse recovery time		—	—	150	ns
Q _{rr} (Note 1)	Reverse recovery charge		—	5.8	—	μC
VEC(Note 1)	Emitter-collector voltage	IE = 150A, VGE = 0V	—	—	3.8	V
R _{th(j-c)Q}	Thermal resistance	IGBT part (1/6 module)*1	—	—	0.14	°C/W
R _{th(j-c)R}		FWDi part (1/6 module)*1	—	—	0.23	°C/W
R _{th(c-f)}	Contact thermal resistance	Case to fin, Thermal compound Applied (1/6 module)*2	—	0.051	—	°C/W
RG	External gate resistance		2.1	—	31	Ω

*1 : Tc measured point is just under the chips.

If you use this value, R_{th(f-a)} should be measured just under the chips.

*2 : Typical value is measured by using Shin-etsu Silicone "G-746".

Note 1. IE, VEC, t_{rr} & Q_{rr} represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).

2. Pulse width and repetition rate should be such that the device junction temp. (Tj) does not exceed Tj_{max} rating.

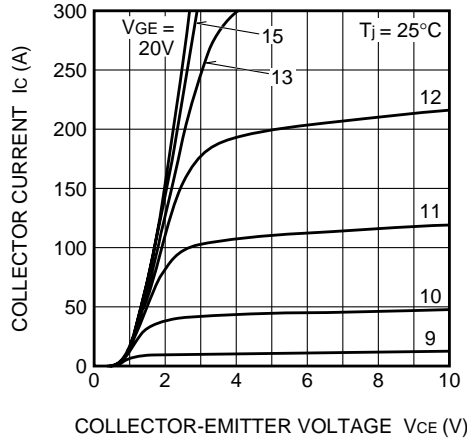
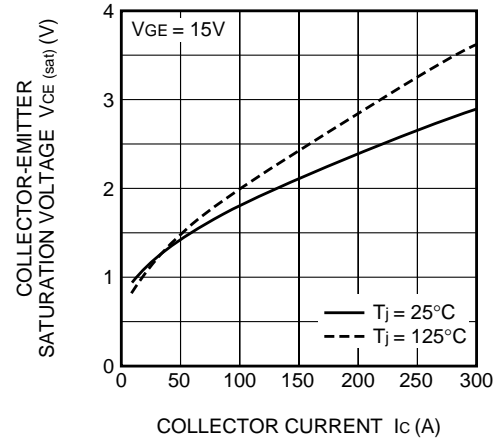
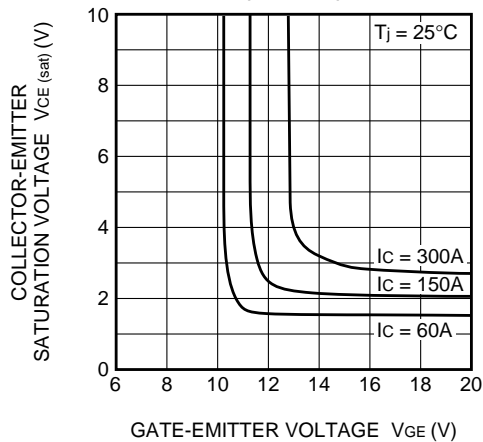
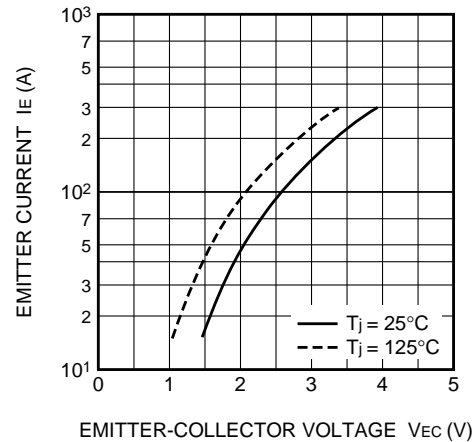
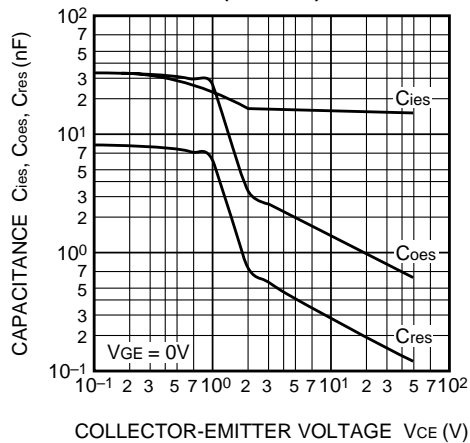
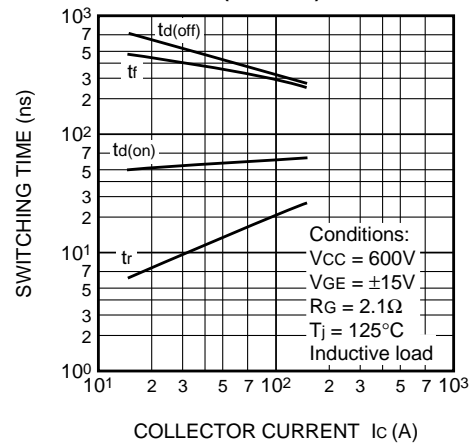
3. Junction temperature (Tj) should not increase beyond 150°C.

4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

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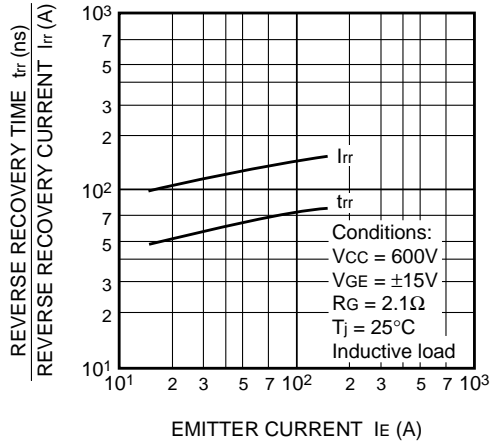
PERFORMANCE CURVES

OUTPUT CHARACTERISTICS
(TYPICAL)COLLECTOR-EMITTER SATURATION
VOLTAGE CHARACTERISTICS
(TYPICAL)COLLECTOR-EMITTER SATURATION
VOLTAGE CHARACTERISTICS
(TYPICAL)FREE-WHEEL DIODE
FORWARD CHARACTERISTICS
(TYPICAL)CAPACITANCE- V_{CE}
CHARACTERISTICS
(TYPICAL)HALF-BRIDGE
SWITCHING CHARACTERISTICS
(TYPICAL)

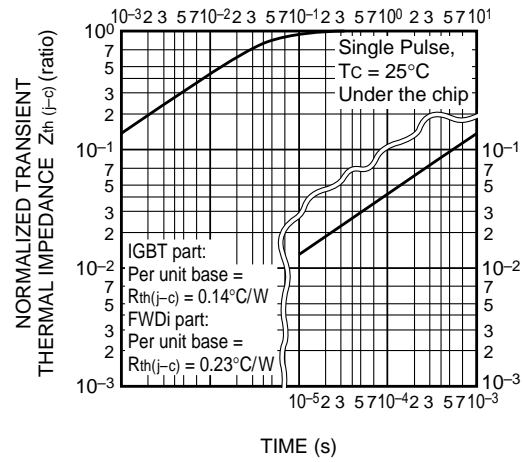
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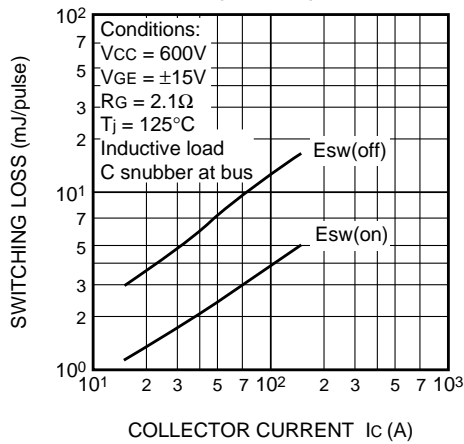
REVERSE RECOVERY CHARACTERISTICS OF FREE-WHEEL DIODE (TYPICAL)



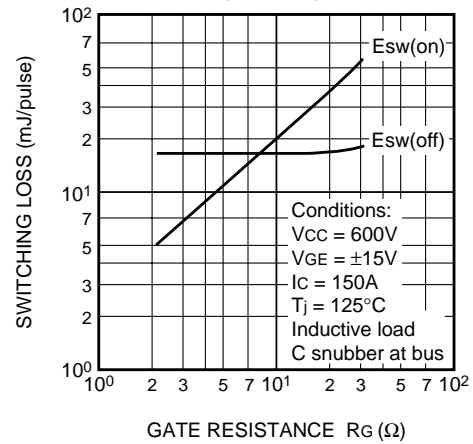
TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (IGBT part & FWDi part)



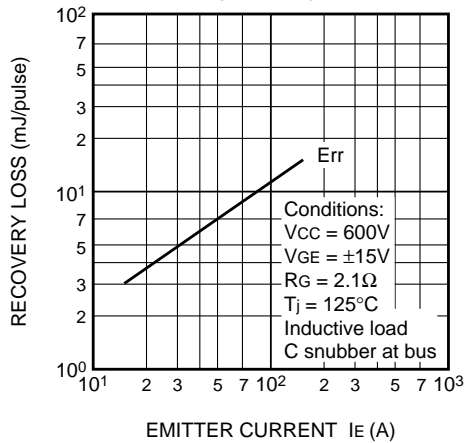
SWITCHING LOSS vs. COLLECTOR CURRENT (TYPICAL)



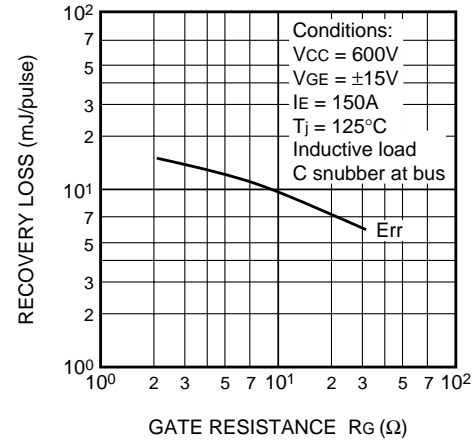
SWITCHING LOSS vs. GATE RESISTANCE (TYPICAL)



RECOVERY LOSS vs. IE (TYPICAL)



RECOVERY LOSS vs. GATE RESISTANCE (TYPICAL)



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